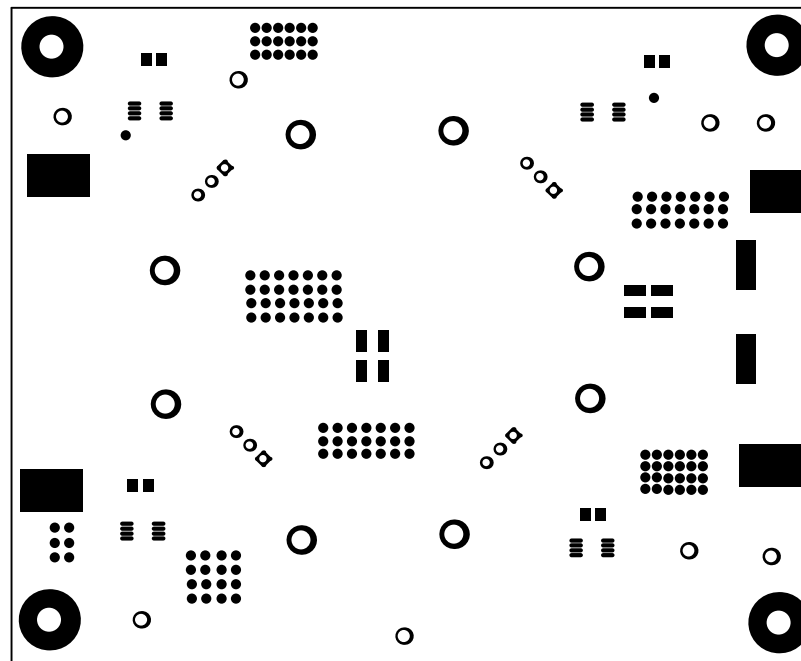
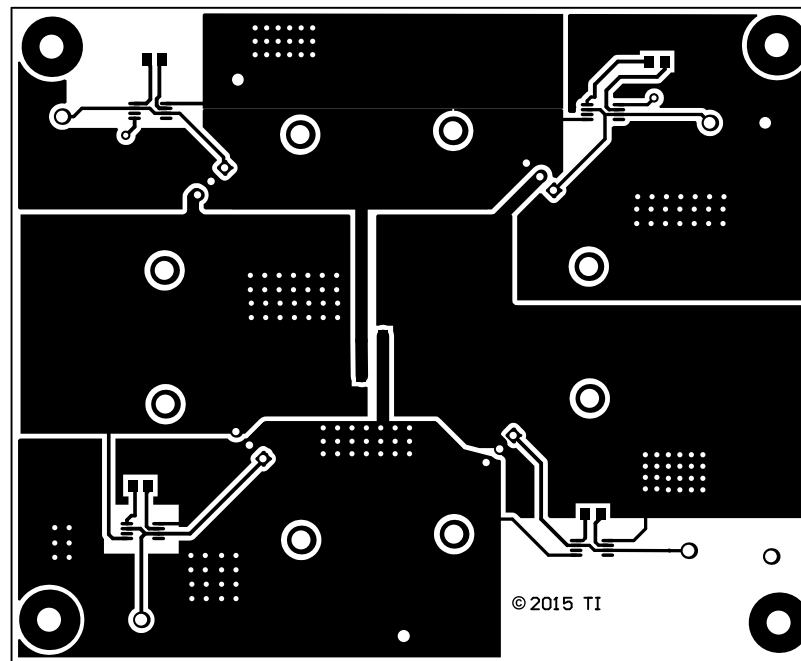


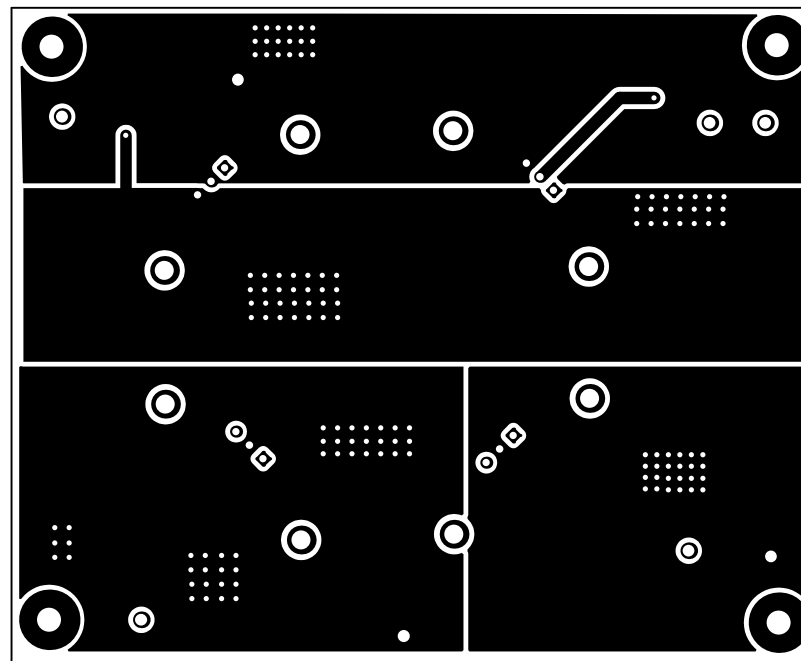
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|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA00858 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | | | |
| PLOT NAME = Top Overlay | GENERATED : 11/11/2015 6:10:09 PM | TEXAS INSTRUMENTS | |



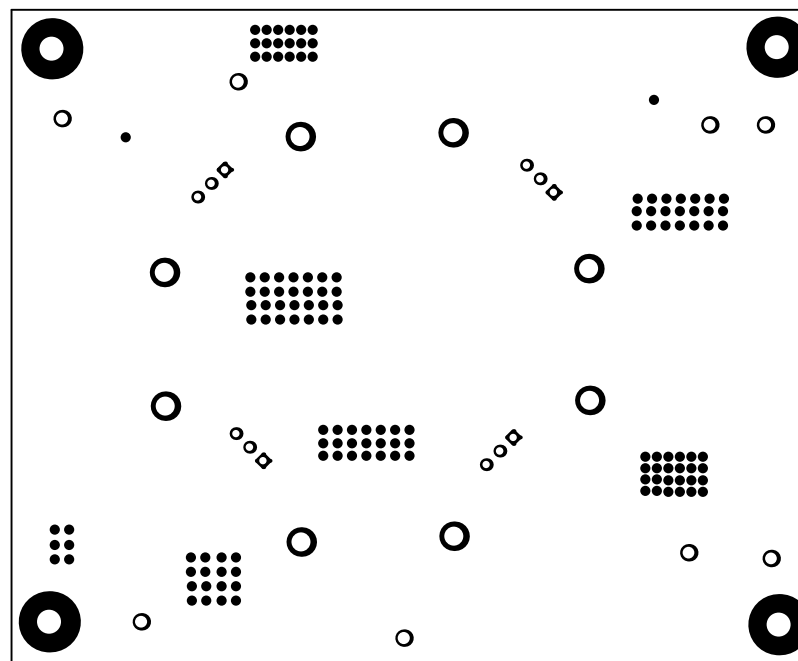
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| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA00858 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 11/11/2015 6:10:09 PM | TEXAS INSTRUMENTS | |



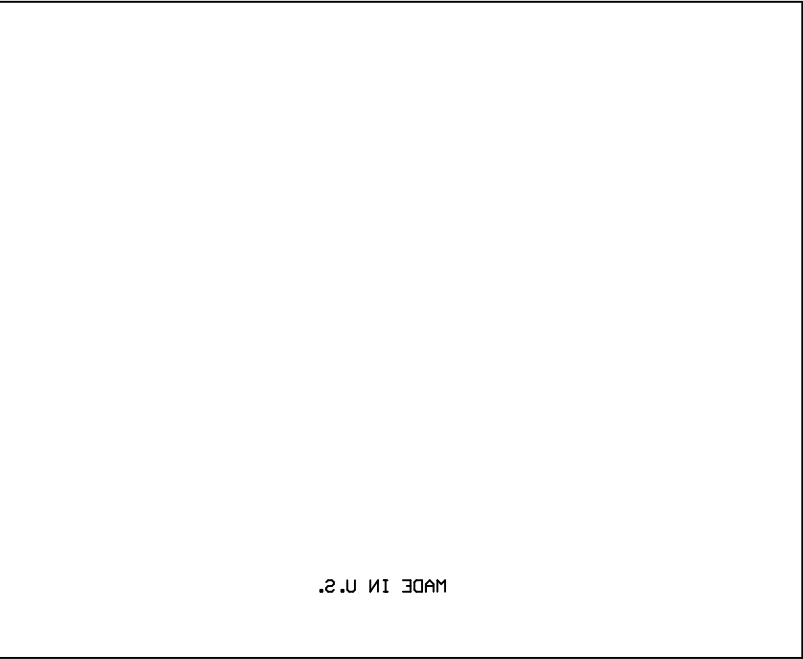
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|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA00858 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | | | |
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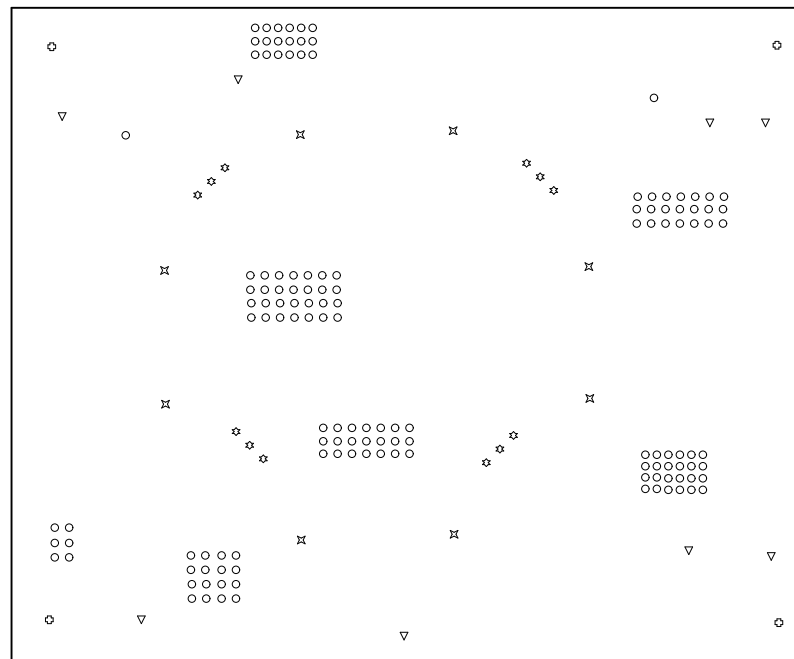
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|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA00858 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 11/11/2015 6:10:11 PM | TEXAS INSTRUMENTS | |



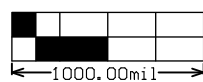
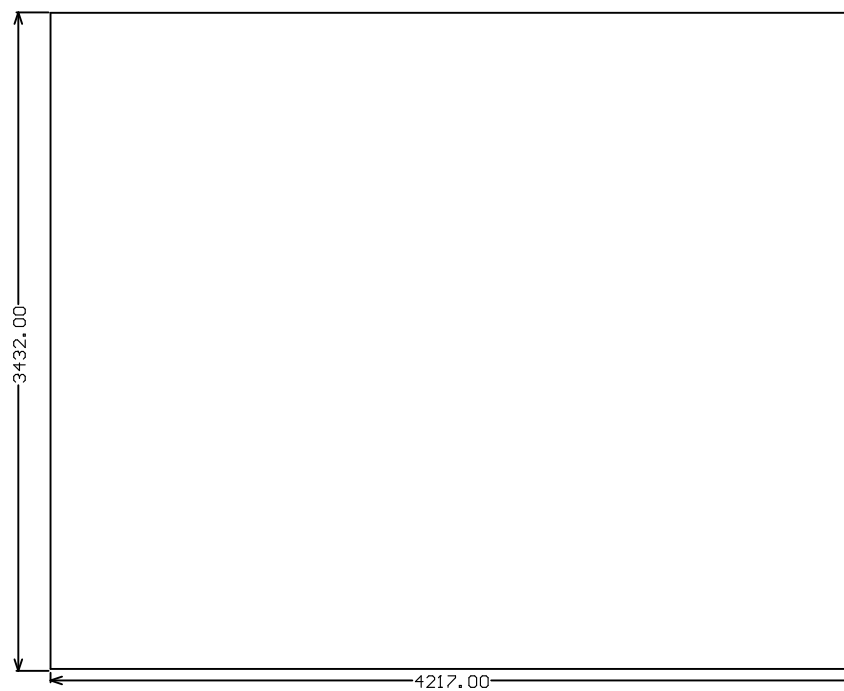
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA00858 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 11/11/2015 6:10:12 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA00858 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 11/11/2015 6:10:12 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA00858 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 11/11/2015 6:10:13 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA00858 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | | | |
| PLOT NAME = Board Dimensions | GENERATED : 11/11/2015 6:10:14 PM | TEXAS INSTRUMENTS | |

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